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# Surface mounting technology —

## Part 2: Transportation and storage conditions of surface mounting devices (SMD) — Application guide

The European Standard EN 61760-2:2007 has the status of a  
British Standard

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This British Standard is the UK implementation of EN 61760-2:2007. It is identical to IEC 61760-2:2007. It supersedes BS EN 61760-2:1998 which is withdrawn.

The UK participation in its preparation was entrusted to Technical Committee EPL/501, Electronic assembly technology.

A list of organizations represented on this committee can be obtained on request to its secretary.

This publication does not purport to include all the necessary provisions of a contract. Users are responsible for its correct application.

**Compliance with a British Standard cannot confer immunity from legal obligations.**

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**Amendments issued since publication**

Amd. No.	Date	Comments

English version

**Surface mounting technology -  
Part 2: Transportation and storage conditions  
of surface mounting devices (SMD) -  
Application guide  
(IEC 61760-2:2007)**

Technique du montage en surface -  
Partie 2: Transport et stockage  
des composants pour montage  
en surface (CSM) -  
Guide d'application  
(CEI 61760-2:2007)

Oberflächenmontagetechnik -  
Teil 2: Transport- und  
Lagerungsbedingungen  
von oberflächenmontierbaren  
Bauelementen (SMD) -  
Anwendungsleitfaden  
(IEC 61760-2:2007)

This European Standard was approved by CENELEC on 2007-05-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Bulgaria, Cyprus, the Czech Republic, Denmark, Estonia, Finland, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, the Netherlands, Norway, Poland, Portugal, Romania, Slovakia, Slovenia, Spain, Sweden, Switzerland and the United Kingdom.

**CENELEC**

European Committee for Electrotechnical Standardization  
Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

**Central Secretariat: rue de Stassart 35, B - 1050 Brussels**

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## Foreword

The text of document 91/569/CDV, future edition 2 of IEC 61760-2, prepared by IEC TC 91, Electronics assembly technology, was submitted to the IEC-CENELEC parallel Unique Acceptance Procedure and was approved by CENELEC as EN 61760-2 on 2007-05-01.

This European Standard supersedes EN 61760-2:1998.

The main changes with regard to EN 61760-2:1998 concern:

EN 61760-2:2007 was updated and editorially revised. Specific reference is made to:

- EN 61340-5-1: Electrostatics – Part 5-1: Protection of electronic devices from electrostatic phenomena – General requirements
- EN 61340-5-2: Electrostatics – Part 5-2: Protection of electronic devices from electrostatic phenomena – User guide

For convenience of the reader, an informative Annex A was added, which contains information about the climatic and mechanical conditions during transportation and storage (extracted from EN 60721-3-1 and EN 60721-3-2).

The following dates were fixed:

- latest date by which the EN has to be implemented  
at national level by publication of an identical  
national standard or by endorsement (dop) 2008-02-01
- latest date by which the national standards conflicting  
with the EN have to be withdrawn (dow) 2010-05-01

Annex ZA has been added by CENELEC.

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## Endorsement notice

The text of the International Standard IEC 61760-2:2007 was approved by CENELEC as a European Standard without any modification.

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## **SURFACE MOUNTING TECHNOLOGY –**

### **Part 2: Transportation and storage conditions of surface mounting devices (SMD) – Application guide**

#### **1 Scope and object**

This International Standard describes the transportation and storage conditions for surface mounting devices (SMDs) that are fulfilled in order to enable trouble-free processing of surface mounting devices, both active and passive. (Conditions for printed boards are not taken into consideration.)

The object of this standard is to ensure that users of SMDs receive and store products that can be further processed (e.g. positioned, soldered) without prejudice to quality and reliability. Improper transportation and storage of SMDs may cause deterioration and result in assembly problems such as poor solderability, delamination and "popcorning".

#### **2 Normative references**

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60286-3: *Packaging of components for automatic handling – Part 3: Packaging of leadless components on continuous tapes*

IEC 60286-4: *Packaging of components for automatic handling – Part 4: Stick magazines for electronic components encapsulated in packages of form **E** and **G***

IEC 60286-5: *Packaging of components for automatic handling – Part 5: Matrix trays*

IEC 60286-6: *Packaging of components for automatic handling – Part 6: Bulk case packaging for surface mounting components*

IEC 60721-3-1: *Classification of environmental conditions – Part 3: Classification of groups of environmental parameters and their severities – Section 1: Storage*

IEC 60721-3-2: *Classification of environmental conditions – Part 3: Classification of groups of environmental parameters and their severities – Section 2: Transportation*

IEC 60749 (all parts), *Semiconductor devices – Mechanical and climatic test methods*

IEC/TS 61340-5-1: *Electrostatics – Part 5-1: Protection of electronic devices from electrostatic phenomena – General requirements*

IEC/TS 61340-5-2: *Electrostatics – Part 5-2: Protection of electronic devices from electrostatic phenomena – User guide*